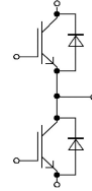


62mm module with trench FS IGBT

FEATURES

- High efficiency
- Low stray inductance design
- Optimized for fast switching
- Maximum junction temperature 175°C
- RoHS compliant

AS62



RoHS
COMPLIANT

HALOGEN
FREE
AVAILABLE

MECHANICAL DATA

- Case: AS62
- Case material: UL flammability classification rating 94V-0

MAXIMUM RATINGS, IGBT

$T_{vj}=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Collector-emitter Voltage@ $T_{vj} = 25^{\circ}\text{C}$	V_{CES}	1700	V
Continuous Collector Current @ $T_C=100^{\circ}\text{C}, T_{vj\ max} = 175^{\circ}\text{C}$	I_C	200	A
Pulsed Collector Current, $t_p = 1\text{ms}$	I_{CRM}	400	A
Power Dissipation @ $T_C=25^{\circ}\text{C}, T_{vj\ max} = 175^{\circ}\text{C}$	P_{tot}	1666	W
Gate-emitter Peak Voltage	V_{GES}	± 20	V
Temperature Under Switching Conditions	T_{vjop}	-40 to +150	$^{\circ}\text{C}$

62mm module with trench FS IGBT
CHARACTERISTICS, IGBT
 $T_{vj}=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Test Conditions	Symbol	Value			Unit
			Min.	Nom.	Max.	
Collector-emitter Saturation Voltage	$V_{GE}=15\text{V}$, $I_C=200\text{A}$	$V_{CE(sat)}$	-	2.1	-	V
Gate Threshold Voltage	$V_{GE}=V_{CE}$, $I_C=8\text{mA}$,	$V_{GE(th)}$	4.8	5.8	6.8	V
Collector-emitter Leakage Current	$V_{CE}=1700\text{V}$, $V_{GE}=0\text{V}$	I_{CES}	-	-	2	mA
Gate Leakage Current	$V_{GE}=\pm 20\text{V}$, $V_{CE}=0\text{V}$	I_{GES}	-	-	± 200	nA
Input Capacitance	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$ $f=1\text{MHz}$	C_{ies}	-	18.7	-	nF
Reverse Transfer Capacitance		C_{res}	-	0.58	-	
Internal Gate Resistor		R_{Gint}	-	4.6	-	Ω
Turn-on Delay Time	$V_{CC}=900\text{V}$, $V_{GE}=-15/15\text{V}$, $I_C=200\text{A}$, $R_G=3.3\ \Omega$, Inductive load $T_{vj}=25^{\circ}\text{C}$	$t_{d(on)}$	-	196	-	ns
Rise Time		t_r	-	88	-	
Turn-off Delay Time		$t_{d(off)}$	-	484	-	
Fall Time		t_f	-	421	-	
Turn-on Energy			E_{on}	-	58.1	-
Turn-off Energy		E_{off}	-	38	-	
Short Circuit Withstand Time	$V_{CC}=900\text{V}$, $V_{GE}\leq 15\text{V}$	t_{sc}	-	10	-	μs
Thermal Resistance, junction to case		$R_{th(j-c)}$	-	-	0.09	K/ W
Thermal Resistance, junction to heatsink		$R_{th(j-h)}$	-	0.04	-	K/ W

62mm module with trench FS IGBT

MAXIMUM RATINGS, Diode

$T_{vj}=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Test Conditions	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	$T_{vj}=25^{\circ}\text{C}$	V_{RRM}	1700	V
Continuous DC Forward Current	$T_C=100^{\circ}\text{C}$	I_F	200	A
Repetitive Peak Forward Current	$t_p=1\text{ ms}$	I_{FRM}	400	A
Temperature Under Switching Conditions		T_{vjop}	-40 to +150	A

CHARACTERISTICS, Diode

$T_{vj}=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Test Condition	Symbol	Value			Unit
			Min.	Nom.	Max.	
Diode Forward Voltage	$I_F=200\text{A}, V_{GE}=0\text{ V}, T_{vj}=25^{\circ}\text{C}$	V_F	-	1.78	-	V
Peak Reverse Recovery Current	$I_F=200\text{A}, V_R=900\text{ V}, V_{GE}=-15\text{V}, R_G=3.3\Omega, T_{vj}=25^{\circ}\text{C}$	I_{RR}	-	177	-	A
Recovered Charge		Q_{RR}	-	35.7	-	μC
Reverse Recovery Energy		E_{rec}	-	21.9	-	mJ
Thermal Resistance, junction to case		$R_{th(j-c)}$	-	-	0.15	K/ W
Thermal Resistance, junction to heatsink		$R_{th(j-h)}$	-	0.04	-	K/ W

CHARACTERISTICS, Module

$T_{vj}=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Test Condition	Symbol	Value			Unit
			Min.	Nom.	Max.	
Isolation Test Voltage	RMS, $f=50\text{Hz}, t=1\text{ min}$	V_{ISOL}	4	-	-	kW
Mounting Torque	Mounting Screw:M6	M	3.0	-	5.0	K/ W
Weight		G	-	320	-	g
Storage Temperature Range		T_{stg}	-40 to +150			K/ W

RATINGS AND CHARACTERISTIC CURVES

$$I_c = f(V_{CE})$$

$$V_{GE} = 15V$$

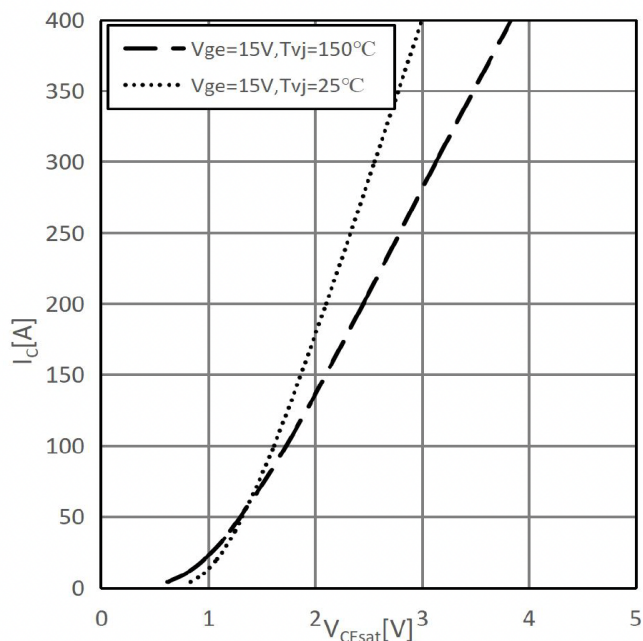


Fig 1. Output characteristic, IGBT

$$I_c = f(V_{CE})$$

$$T_{vj} = 150^\circ C$$

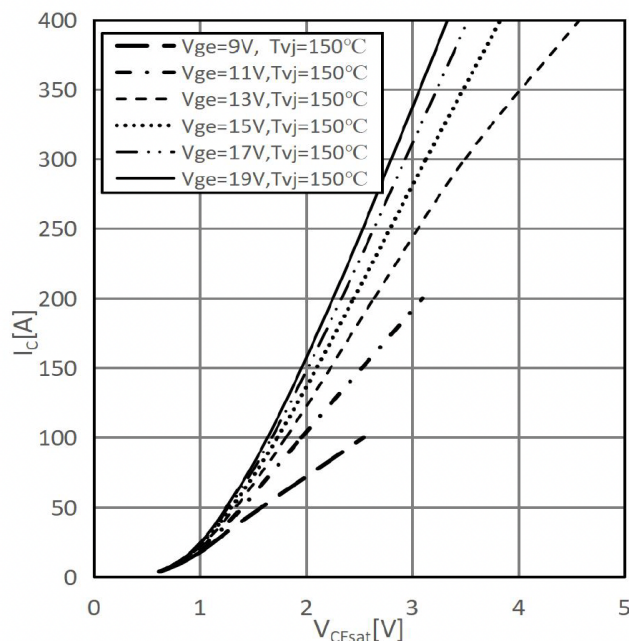


Fig 2. Output characteristic, IGBT

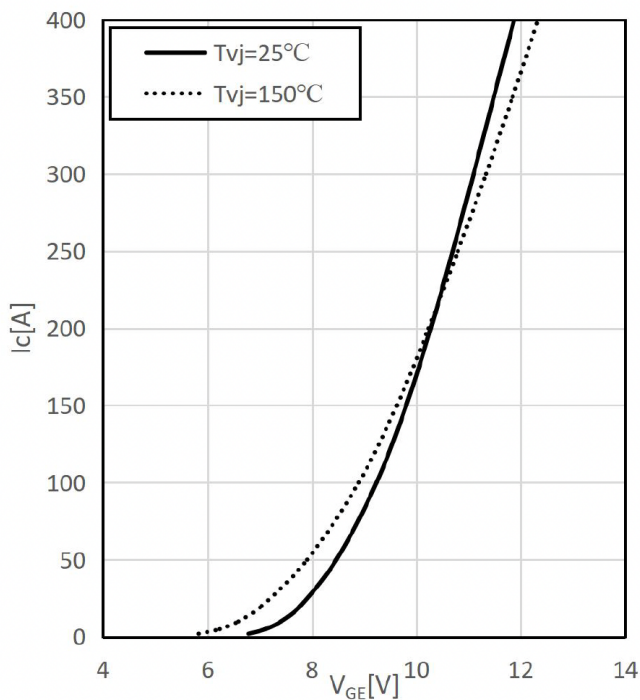


Fig 3. Transfer characteristic, IGBT

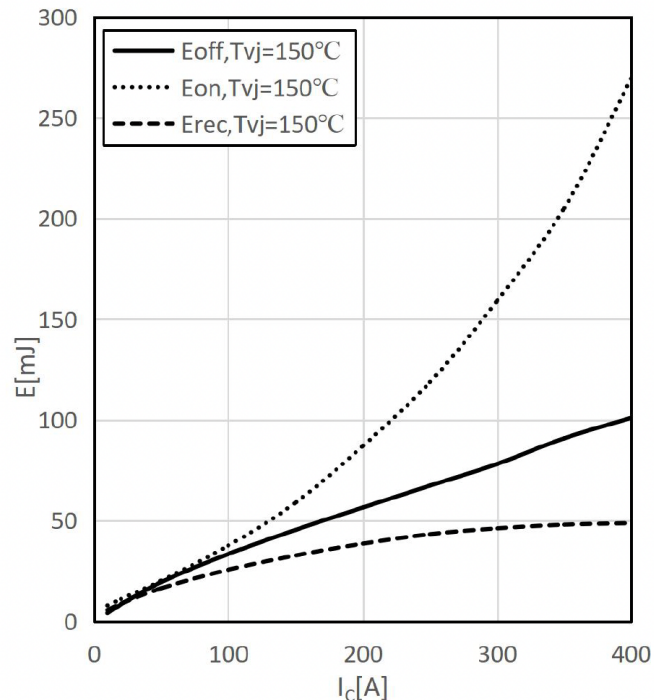


Fig 4. Switching losses

RATINGS AND CHARACTERISTIC CURVES

$$E_{on}=f(R_G), E_{off}=f(R_G), E_{rec}=f(R_G)$$

$$V_{GE}=\pm 15V, I_C=200A, V_{CE}=900V, T_{vj}=150^\circ C$$

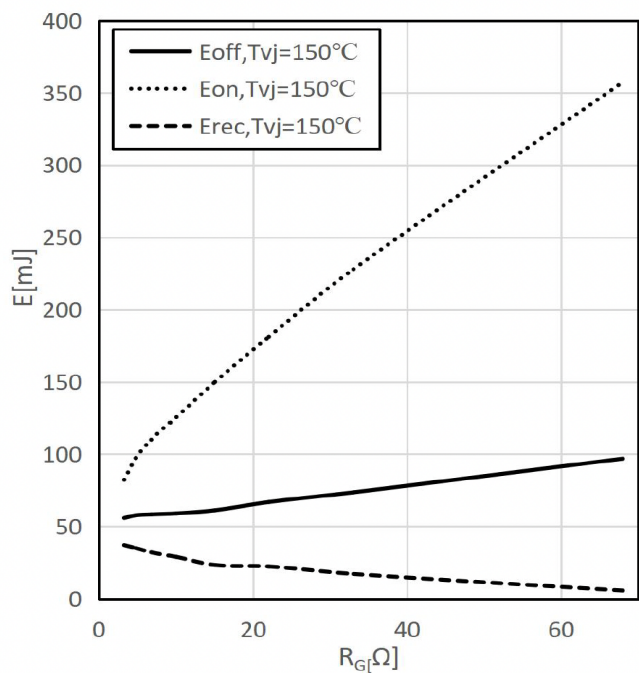


Fig 5. Switching losses

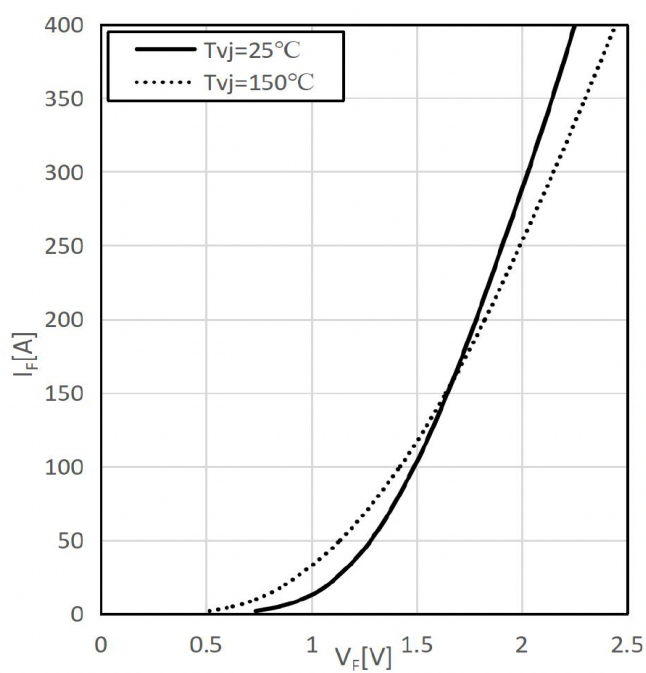


Fig 6. Forward characteristic, Diode

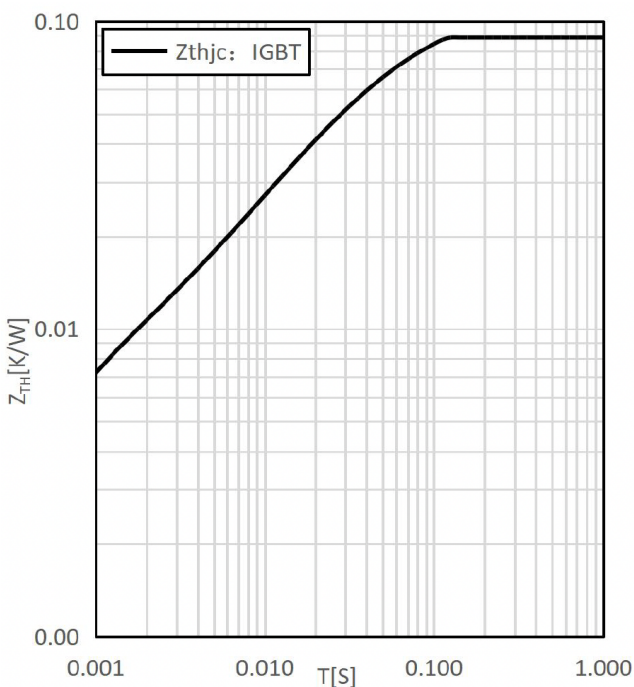


Fig 7. Transient thermal impedance, IGBT

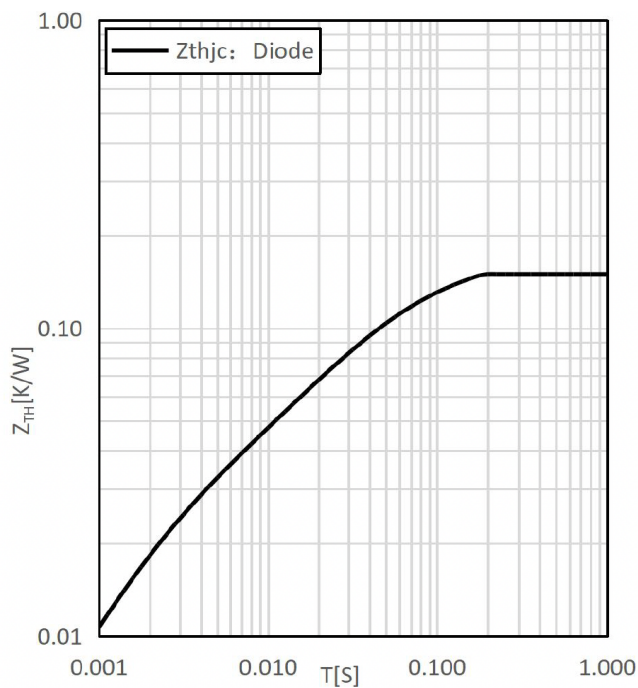
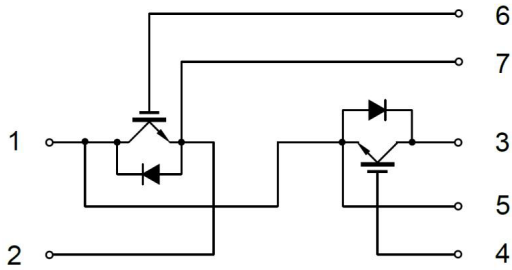
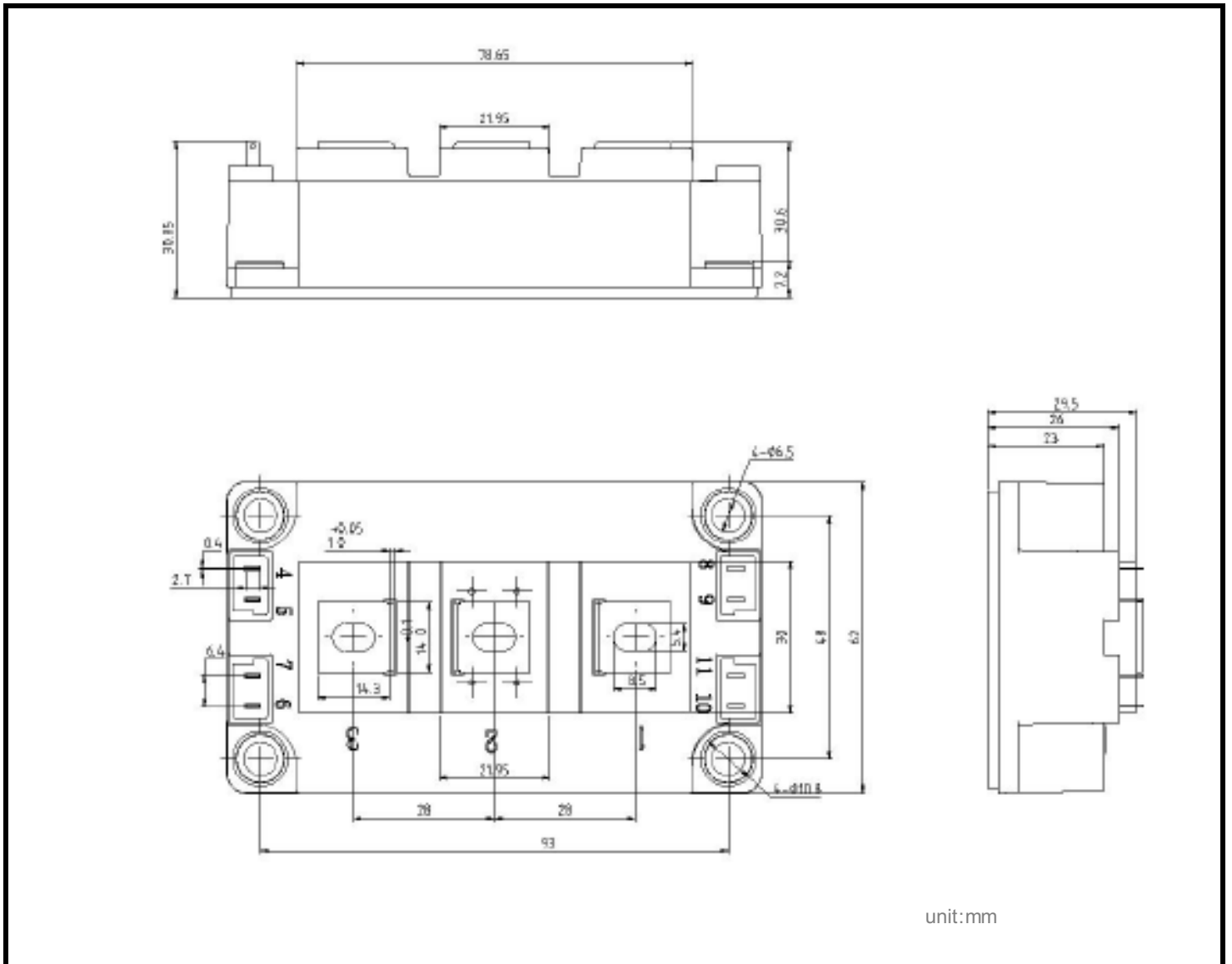


Fig 8. Transient thermal impedance, Diode

PACKAGE OUTLINE DIMENSIONS



PACKAGE OUTLINE DIMENSIONS



unit:mm